

AMENDMENTS TO THE CLAIMS

Please amend the Claims as follows. Insertions are shown underlined while deletions are ~~struck through~~.

1 (currently amended): A ~~manufacturing method for manufacturing of~~ a ceramic green sheet comprising steps of;

preparing a carrier sheet comprising a base film and an adhesive layer;

forming a predetermined electrode pattern on ansaid adhesive layer, said adhesive layer being separable from said electrode pattern by being heated or an adhesive layer separable by being cured with UV of a carrier sheet, wherein the carrier sheet comprising the separable adhesive layer on one side of a base film; and

forming a ceramic green sheet withapplying a ceramic slurry on the separable adhesive layer with theonto (A) said electrode pattern formed on said adhesive layer thereonand (B) an exposed surface of said adhesive layer to form a ceramic binder layer which adheres to said electrode pattern and said exposed surface, thereby forming a ceramic green sheet on the carrier sheet.

[2 (canceled)]

3 (currently amended): ~~The manufacturing~~A method ~~offor manufacturing thea~~ ceramic green sheet ~~according to Claim 1~~comprising steps of:

preparing a carrier sheet comprising a base film and an adhesive layer;

forming a predetermined electrode pattern on said adhesive layer, said adhesive layer being separable from said electrode pattern by heating; and

applying a ceramic slurry onto (A) said electrode pattern formed on said adhesive layer and (B) an exposed surface of said adhesive layer to form a ceramic binder layer which adheres to said electrode pattern and said exposed surface, thereby forming a ceramic green sheet on the carrier sheet,

wherein the adhesive layer separable by ~~being heated~~heating comprises thermal expandable fine particles.

4 (currently amended): ~~The manufacturing method of the ceramic green sheet according to Claim 4~~3, wherein a dynamic modulus of elastic of an adhesive forming the

adhesive layer separable by ~~being heated~~heating is in a range of 5×10^3 to 1×10^6 Pa at a temperature of 23 degrees C to 150 degrees C.

5 (currently amended): ~~The~~A manufacturing method ~~effor manufacturing thea~~ ceramic green sheet ~~aeecording to Claim 1~~comprising steps of:

preparing a carrier sheet comprising a base film and an adhesive layer;

forming a predetermined electrode pattern on said adhesive layer, said adhesive layer being separable from said electrode pattern by heating; and

applying a ceramic slurry onto (A) said electrode pattern formed on said adhesive layer and (B) an exposed surface of said adhesive layer to form a ceramic binder layer which adheres to said electrode pattern and said exposed surface, thereby forming a ceramic green sheet on the carrier sheet,

wherein the adhesive layer separable by ~~being heated~~heating comprises a side chain crystalline resin.

6 (currently presented): ~~The manufacturing method of the ceramic green sheet according to Claim 4~~5, wherein an adhesive strength to stainless steel of the adhesive layer separable by ~~being heated~~heating is more than 0.1 N / 20mm at ordinary temperature (23 degrees C) and is no more than 0.1 N / 20mm when heated.

7 (currently amended): ~~The manufacturing method of the ceramic green sheet according to Claim 1~~, wherein an adhesive strength at ordinary temperature (23 degrees C) to stainless steel of the adhesive layer separable by being cured with UV is more than 0.1 N / 20mm before UV irradiation and no more than 0.1N / 20mm after UV irradiation.

8 (currently amended): ~~A manufacturing method effor manufacturing a multilayer ceramic electronic component comprising steps of;~~

~~laminating a ceramic green sheet onto other ceramic green sheets, after manufacturing thea ceramic green sheet by manufacturingthe method according to Claim 1;~~

laminating the ceramic green sheet onto other ceramic green sheets; and

~~and separating thea carrier sheet from the ceramic green sheet by being heated or irradiated with UV.~~

9 (currently amended): ~~A carrier sheet for ceramic green sheets used for the manufacturing method of the ceramic green sheet according to Claim 1, said carrier sheet~~

comprising ~~an adhesive layer separable by being heated or a base film and~~ an adhesive layer separable by being cured with UV on one side of asaid base film.

10 (currently amended): A multilayer ceramic electronic component obtained by the ~~manufacturing method of a multilayer ceramic electronic component according to Claim 8.~~

11 (currently amended): A carrier sheet for ceramic green sheets used for the ~~manufacturing method of the multilayer ceramic electronic component according to Claim 8, said carrier sheet comprising an adhesive layer separable by being heated or a base film and~~ an adhesive layer separable by being cured with UV on one side of asaid base film.

12 (currently amended): The ~~manufacturing method of the ceramic green sheet according to Claim 13,~~ wherein a dynamic modulus of elastic of an adhesive forming the adhesive layer separable by ~~being heated~~ heating is in a range of 5×10^4 to 8×10^5 Pa at a temperature of 23 degrees C to 150 degrees C.

13 (currently amended): The ~~manufacturing method of the ceramic green sheet according to Claim 15,~~ wherein an adhesive strength to stainless steel of the adhesive layer separable by ~~being heated~~ heating is more than 0.2 N / 20mm at ordinary temperature (23 degrees C) and is no more than 0.05 N / 20mm when heated.

14 (currently amended): The ~~manufacturing method of the ceramic green sheet according to Claim 1,~~ wherein an adhesive strength at ordinary temperature (23 degrees C) to stainless steel of the adhesive layer separable by being cured with UV is more than 0.2 N / 20mm before UV irradiation and no more than 0.05 N / 20mm after UV irradiation.

15 (new): The method according to Claim 3, wherein the adhesive layer separable by heating foams when heated, and makes separation with ease.

16 (new): The method according to Claim 1, which additionally comprising separating the carrier sheet from the ceramic green sheet by being cured with UV.

17 (new): The method according to Claim 3, which additionally comprising separating the carrier sheet from the ceramic green sheet by heating.

18 (new): The method according to Claim 5, which additionally comprising separating the carrier sheet from the ceramic green sheet by heating.

19 (new): A method for manufacturing a multilayer ceramic electronic component comprising steps of:

manufacturing a ceramic green sheet by the method according to Claim 3;

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laminating the ceramic green sheet onto other ceramic green sheets; and
separating a carrier sheet from the ceramic green sheet by heating.

20 (new): A method for manufacturing a multilayer ceramic electronic component
comprising steps of:

manufacturing a ceramic green sheet by the method according to Claim 5;
laminating the ceramic green sheet onto other ceramic green sheets; and
separating a carrier sheet from the ceramic green sheet by heating.

21 (new): A carrier sheet for ceramic green sheets used for the method according to
Claim 3, said carrier sheet comprising a base film and an adhesive layer separable by heating on
one side of said base film, wherein said adhesive layer comprises thermal expandable fine
particles.

22 (new): A carrier sheet for ceramic green sheets used for the method according to
Claim 5, said carrier sheet comprising a base film and an adhesive layer separable by heating on
one side of said base film, wherein said adhesive layer comprises a side chain crystalline resin.